

ABSTRACT

An apparatus including a contact point formed on a device layer of a circuit substrate or interconnect layer on a substrate; a first dielectric layer including cubic boron nitride on the substrate; and a different second dielectric layer on the substrate and separated from the device layer by the first dielectric layer. Also, an apparatus including a circuit substrate including a device layer and a composite dielectric layer. The composite dielectric includes a first dielectric material including cubic boron nitride and a different second dielectric material. The first dielectric material surrounds the second dielectric material.